

# LINEAR SYSTEMS

Over Three Decades of Quality Through Innovation

## SD-SST210/214

### N-CHANNEL LATERAL DMOS SWITCH

PART NUMBER	$V_{(BR)DS}$ Min (V)	$V_{(GS)th}$ Max (V)	$r_{DS(on)}$ Max ( $\Omega$ )	$C_{rss}$ Max (pF)	$t_{ON}$ Max (ns)
SD210DE	30	1.5	45 @ $V_{GS}=10V$	0.5	2
SD214DE	20	1.5	45 @ $V_{GS}=10V$	0.5	2
SST210	30	1.5	50 @ $V_{GS}=10V$	0.5	2
SST214	20	1.5	50 @ $V_{GS}=10V$	0.5	2

## PRODUCT SUMMARY

### Features

- Ultra-High Speed Switching— $t_{ON}$ : 1ns
- Ultra-Low Reverse Capacitance: 0.2pF
- Low Guaranteed  $r_{DS}$  @5V
- Low Turn-On Threshold Voltage
- N-Channel Enhancement Mode

### Benefits

- High-Speed System Performance
- Low Insertion Loss at High Frequencies
- Low Transfer Signal Loss
- Simple Driver Requirement
- Single Supply Operation

### Applications

- Fast Analog Switch
- Fast Sample-and-Holds
- Pixel-Rate Switching
- DAC Deglitchers
- High-Speed Driver

## Description

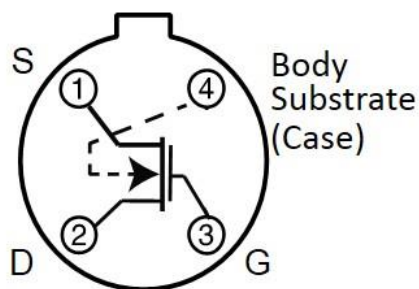
The SD210DE/214 and SST210/214 are enhancement-mode MOSFETs designed for high speed low-glitch switching in audio, video and high-frequency applications. The SD214DE and SST214 are normally used for  $\pm 10$ -V analog switching. These MOSFETs utilize lateral construction to achieve low capacitance and ultra-fast switching speeds. These MOSFETs do not

have a gate protection Zener diode which results in lower gate leakage and  $\pm$  voltage capability from gate to substrate. A polysilicon gate is featured for manufacturing reliability.

For similar products see: quad array—SD5000/5400 series, Zener protected—SD211DE/SST211 Series.

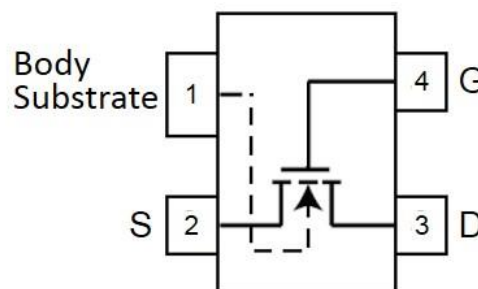
## Top Views

### SD210DE, SD214DE



TO-206AF  
(TO-72)

### SST210, SST214



TO-253  
(SOT-143)

## Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

Gate-Drain, Gate-Source Voltage	$\pm 40\text{V}$	Source-Substrate Voltage	(SD210DE/SST210) $\dots\dots\dots 15\text{V}$ (SD210DE/SST210) $\dots\dots\dots 25\text{V}$
Gate-Substrate Voltage	$\pm 30\text{V}$	Drain Current	$\dots\dots\dots .50\text{mA}$
Drain-Source Voltage	(SD210DE/SST210) $\dots\dots\dots 30\text{V}$ (SD214DE/SST214) $\dots\dots\dots 20\text{V}$	Lead Temperature (1/16" from case for 10 seconds)	$\dots\dots\dots 300^\circ\text{C}$
Source-Drain Voltage	(SD210DE/SST210) $\dots\dots\dots 10\text{V}$ (SD214DE/SST214) $\dots\dots\dots 20\text{V}$	Storage Temperature	$\dots\dots\dots -65$ to $150^\circ\text{C}$
Drain-Substrate Voltage	(SD210DE/SST210) $\dots\dots\dots 30\text{V}$ (SD214DE/SST214) $\dots\dots\dots 25\text{V}$	Operating Junction Temperature	$\dots\dots\dots -55$ to $125^\circ\text{C}$
		Power Dissipation*	$\dots\dots\dots .300\text{mW}$

Note:  
\* Derate  $3\text{mW}/^\circ\text{C}$  above  $25^\circ\text{C}$

## Specifications<sup>a</sup>

PARAMETER	SYMBOL	TEST CONDITIONS	TYP	LIMITS				UNIT	
				210 Series		214 Series			
				Min	Max	Min	Max		
<b>Static</b>									
Drain - Source Breakdown Voltage	$V_{(BR)DS}$	$V_{GS} = V_{BS} = 0\text{V}, I_D = 10 \mu\text{A}$	35	30				V	
		$V_{GS} = V_{BS} = -5\text{V}, I_D = 10 \text{nA}$	30	10		20			
Source - Drain Breakdown Voltage	$V_{(BR)SD}$	$V_{GD} = V_{BD} = -5\text{V}, I_S = 10 \text{nA}$	22	10		20			
Drain - Substrate Breakdown Voltage	$V_{(BR)DBO}$	$V_{GB} = 0\text{V}, I_D = 10 \text{nA}$ Source Open	35	15		25			
Source - Substrate Breakdown Voltage	$V_{(BR)SBO}$	$V_{GB} = 0\text{V}, I_S = 10 \mu\text{A}$ Drain Open	35	15		25			
Drain - Source Leakage	$I_{DS(off)}$	$V_{GS} = V_{BS} = -5\text{V}$	$V_{DS} = 10\text{V}$	0.4		10		nA	
			$V_{DS} = 20\text{V}$	0.9			10		
Source - Drain Leakage	$I_{SD(off)}$	$V_{GD} = V_{BD} = -5\text{V}$	$V_{SD} = 10\text{V}$	0.5		10			
			$V_{SD} = 20\text{V}$				10		
Gate Leakage	$I_{GBS}$	$V_{DB} = V_{SB} = 0\text{V}, V_{GB} = \pm 40\text{V}$	$\pm 0.001$		$\pm 100$		$\pm 100$	pA	
Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 1 \mu\text{A},$ $V_{SB} = 0\text{V}$	0.8	0.5	1.5	0.1	1.5	V	
Drain - Source On-Resistance	$r_{DS(on)}$	$V_{SB} = 0\text{V}$ $I_D = 1\text{mA}$	$V_{GS} = 5\text{V}$ (SD Series)	58		70		70	$\Omega$
			$V_{GS} = 5\text{V}$ (SST Series)	60		75		75	
			$V_{GS} = 10\text{V}$ (SD Series)	38		45		45	
			$V_{GS} = 10\text{V}$ (SST Series)	40		50		50	
			$V_{GS} = 15\text{V}$	30					
			$V_{GS} = 20\text{V}$	26					
			$V_{GS} = 25\text{V}$	24					

# Specifications<sup>a</sup>

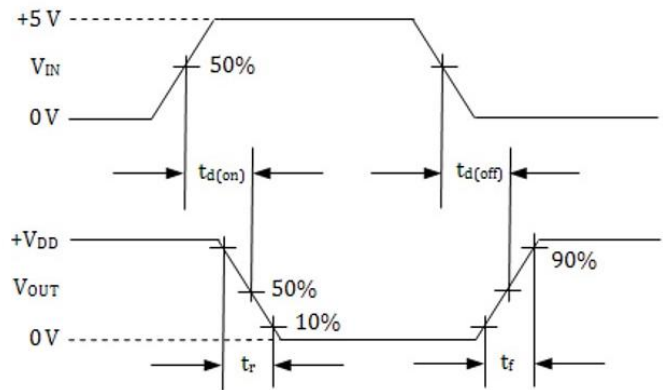
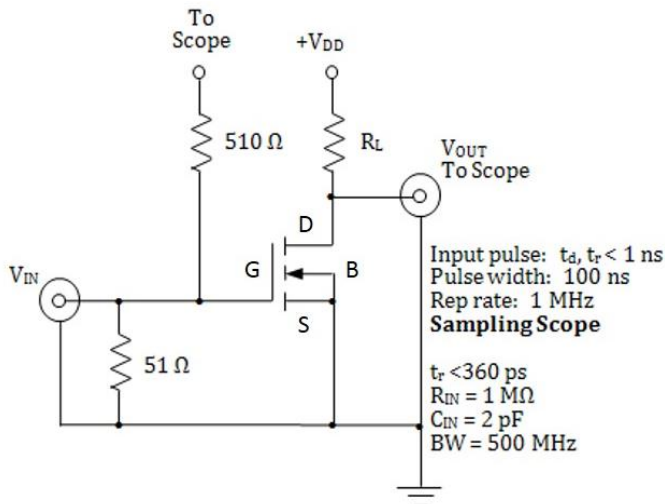
PARAMETER	SYMBOL <sup>b</sup>	TEST CONDITIONS <sup>b</sup>	TYP <sup>c</sup>	LIMITS				UNIT	
				210 Series		214 Series			
				Min	Max	Min	Max		
<b>Dynamic</b>									
Forward Transconductance	$g_{fs}$	$V_{DS} = 10V, V_{SB} = 0V, I_D = 20mA, f = 1kHz$	SD Series	11	10		10		mS
			SST Series	10.5	9		9		
			All	0.9					
Gate Node Capacitance	$C_{(GS+GD+GB)}$	$V_{DS} = 10V, f = 1MHz, V_{GS} = V_{BS} = -15V$	SD Series	2.5		3.5		3.5	pF
Drain Node Capacitance	$C_{(GD+DB)}$			1.1		1.5		1.5	
Source Node Capacitance	$C_{(GS+SB)}$			3.7		5.5		5.5	
Reverse Transfer Capacitance	$C_{rss}$			SST Series	4.2				
			SD Series	0.2		0.5		0.5	
<b>Switching</b>									
Turn-On Time	$t_{D(on)}$	SD Series Only $V_{SB} = 0V, V_{IN} 0 \text{ to } 5V, R_G = 25\Omega, V_{DD} = 5V, R_L = 680\Omega$	0.5		1		1	ns	
	$t_r$		0.6		1		1		
Turn-Off Time	$t_{D(off)}$		2						
	$t_f$		6						

## NOTES:

- $T_A = 25^\circ C$  unless otherwise notes.
- B is the body (substrate) and  $V_{(BR)}$  is breakdown voltage.
- Typical values are for DESIGN AID ONLY, not guaranteed nor subject to production testing.

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## Switching Time Test Circuit



Linear Integrated Systems (LIS), established in 1987, is third-generation precision semiconductor company providing high-quality discrete components. Expertise brought to LIS is based on processes and products developed at Amelco, Union Carbide, Intersil and Micro Power Systems by company Founder John H. Hall. Hall, a protégé of Silicon Valley legend Dr. Jean Hoerni, was the director of IC Development at Union Carbide, Co-Founder and Vice President of R&D at Intersil, and Founder/President of Micro Power Systems.